Hermetic Packages for Integrated Circuits

Ceramic Metal Seal Flatpack Packages (Flatpack)

NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark. Alternately, a tab (dimension k) may be used to identify pin one.

2. If a pin one identification mark is used in addition to a tab, the limits of dimension k do not apply.

3. This dimension allows for off-center lid, meniscus, and glass overrun.

4. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.

5. N is the maximum number of terminal positions.

6. Measure dimension S1 at all four corners.

7. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.

8. Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.


10. Controlling dimension: INCH.